General Purpose Transistors

NPN Silicon

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CEO}	45	V
Collector - Base Voltage	V_{CBO}	50	V
Emitter-Base Voltage	V_{EBO}	5.0	V
Collector Current – Continuous	I _C	500	mAdc

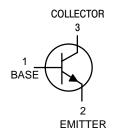
THERMAL CHARACTERISTICS

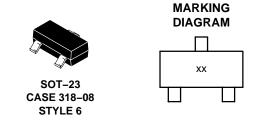
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.



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xx = Specific Device Code BC816-16LT1 = 6A BC817-25LT1 = 6B BC817-40LT1 = 6C

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I _C = –10 mA)	V _(BR) CEO	45	-	-	V
Collector – Emitter Breakdown Voltage (V _{EB} = 0, I _C = –10 μA)	V _(BR) CES	50	-	-	V
Emitter – Base Breakdown Voltage ($I_E = -1.0 \mu A$)	V _{(BR)EBO}	5.0	-	_	V
Collector Cutoff Current $(V_{CB} = 20 \text{ V})$ $(V_{CB} = 20 \text{ V}, T_A = 150^{\circ}\text{C})$	I _{CBO}	- -	- -	100 5.0	nA μA
ON CHARACTERISTICS					
DC Current Gain $ \begin{array}{ll} \text{(I}_{C} = 100 \text{ mA, V}_{CE} = 1.0 \text{ V)} & \text{BC817-16} \\ \text{BC817-25} & \text{BC817-40} \\ \text{(I}_{C} = 500 \text{ mA, V}_{CE} = 1.0 \text{ V)} \end{array} $	h _{FE}	100 160 250 40	- - - -	250 400 600 –	-
Collector – Emitter Saturation Voltage (I _C = 500 mA, I _B = 50 mA)	V _{CE(sat)}	_	-	0.7	V
Base – Emitter On Voltage (I _C = 500 mA, V _{CE} = 1.0 V)	V _{BE(on)}	_	-	1.2	V
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain – Bandwidth Product (I _C = 10 mA, V _{CE} = 5.0 Vdc, f = 100 MHz)	f⊤	100	_	_	MHz
Output Capacitance (V _{CB} = 10 V, f = 1.0 MHz)	C _{obo}	_	10	_	pF

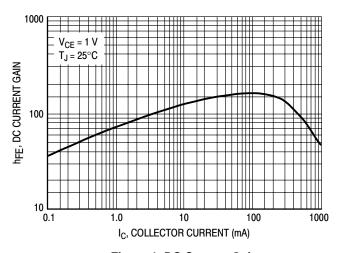


Figure 1. DC Current Gain

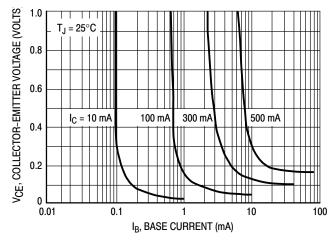


Figure 2. Saturation Region

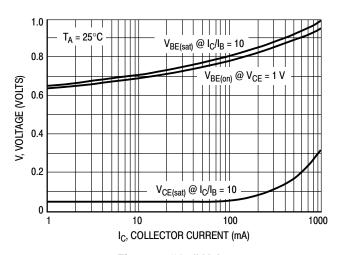


Figure 3. "On" Voltages

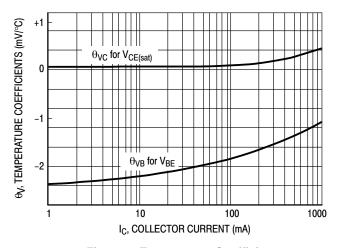


Figure 4. Temperature Coefficients

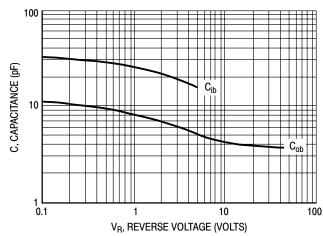


Figure 5. Capacitances

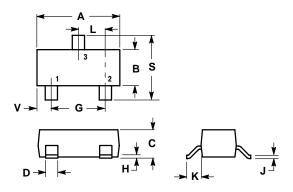
ORDERING INFORMATION

Device	Package	Shipping [†]	
BC817-16LT1	SOT-23	3000 / Tape & Reel	
BC817-16LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel	
BC817-16LT3	SOT-23	10000 / Tape & Reel	
BC817-25LT1	SOT-23	3000 / Tape & Reel	
BC817-25LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel	
BC817-25LT3	SOT-23	10000 / Tape & Reel	
BC817-25LT3G	SOT-23 (Pb-Free)	10000 / Tape & Reel	
BC817-40LT1	SOT-23	3000 / Tape & Reel	
BC817-40LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel	
BC817-40LT3	SOT-23	10000 / Tape & Reel	
SBC817-40LT1	SOT-23	3000 / Tape & Reel	
SBC817-40LT3	SOT-23	10000 / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AH**



- IOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

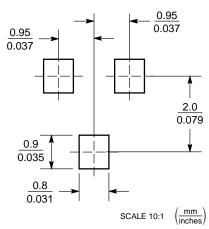
 2. CONTROLLING DIMENSION: INCH.

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

 4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
С	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
V	0.0177	0.0236	0.45	0.60

- STYLE 6: PIN 1. BASE 2. EMITT 3. COLLE
 - EMITTER COLLECTOR
- **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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